## MC74HCT595A

## 8-Bit Serial-Input/Serial or Parallel-Output Shift Register with Latched 3-State Outputs and LSTTL Compatible Inputs

## High-Performance Silicon-Gate CMOS

The MC74HCT595A consists of an 8-bit shift register and an 8-bit D-type latch with three-state parallel outputs. The shift register accepts serial data and provides a serial output. The shift register also provides parallel data to the 8 -bit latch. The shift register and latch have independent clock inputs. This device also has an asynchronous reset for the shift register.

The HCT595A directly interfaces with the SPI serial data port on CMOS MPUs and MCUs. The device inputs are compatible with standard CMOS or LSTTL outputs.

## Features

- Output Drive Capability: 15 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 4.5 to 5.5 V
- Low Input Current: $1.0 \mu \mathrm{~A}$
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 328 FETs or 82 Equivalent Gates
- Improvements over HC595 / HCT595
- Improved Propagation Delays
- $50 \%$ Lower Quiescent Power
- Improved Input Noise and Latchup Immunity
- $\mathrm{Pb}-$ Free Packages are Available*


[^0]

## ORDERING INFORMATION

| Device | Package | Shipping $^{\dagger}$ |
| :--- | :---: | :---: |
| MC74HCT595ADG | SOIC-16 <br> (Pb-Free) | 48 Units / Rail |
| MC74HCT595ADR2G | SOIC-16 <br> (Pb-Free) | 2500 Tape \& Reel |
| MC74HCT595ADTG | TSSOP-16* | 96 Units / Rail |
| MC74HCT595ADTR2G | TSSOP-16* <br> (Pb-Free) | 2500 Tape \& Reel |

$\dagger$ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb -Free.

MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit |
| :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{Cc}}$ | DC Supply Voltage (Referenced to GND) | -0.5 to +7.0 | V |
| $\mathrm{V}_{\text {in }}$ | DC Input Voltage (Referenced to GND) | -0.5 to $\mathrm{V}_{\mathrm{CC}}+0.5$ | V |
| $\mathrm{V}_{\text {out }}$ | DC Output Voltage (Referenced to GND) | -0.5 to $V_{C C}+0.5$ | V |
| $1{ }_{\text {in }}$ | DC Input Current, per Pin | $\pm 20$ | mA |
| $\mathrm{I}_{\text {out }}$ | DC Output Current, per Pin | $\pm 35$ | mA |
| ICC | DC Supply Current, $\mathrm{V}_{\mathrm{CC}}$ and GND Pins | $\pm 75$ | mA |
| $\mathrm{P}_{\mathrm{D}}$ | Power Dissipation in Still Air, Package $\dagger$ TSSOP Package $\dagger$ | $\begin{aligned} & 500 \\ & 450 \end{aligned}$ | mW |
| $\mathrm{T}_{\text {stg }}$ | Storage Temperature | -65 to + 150 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\mathrm{L}}$ | Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP, SOIC or TSSOP Package) | 260 | ${ }^{\circ} \mathrm{C}$ |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
$\dagger$ Derating - SOIC Package: $-7 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ from $65^{\circ}$ to $125^{\circ} \mathrm{C}$
TSSOP Package: $-6.1 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ from $65^{\circ}$ to $125^{\circ} \mathrm{C}$

## RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit |
| :---: | :--- | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{CC}}$ | DC Supply Voltage (Referenced to GND) | 4.5 | 5.5 | V |
| $\mathrm{~V}_{\text {in }}, \mathrm{V}_{\text {out }}$ | DC Input Voltage, Output Voltage (Referenced to GND) | 0 | $\mathrm{~V}_{\mathrm{CC}}$ | V |
| $\mathrm{T}_{\mathrm{A}}$ | Operating Temperature Range, All Package Types | -55 | +125 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{t}_{\mathrm{r}}, \mathrm{t}_{\mathrm{f}}$ | Input Rise/Fall Time (Figure 1) | 0 | 500 | ns |

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

| Symbol | Parameter | Test Conditions | $\stackrel{\mathrm{v}_{\mathrm{cc}}}{\mathrm{~V}}$ | Guaranteed Limit |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | -55 to $25^{\circ} \mathrm{C}$ | $\leq 85^{\circ} \mathrm{C}$ | $\leq 125^{\circ} \mathrm{C}$ |  |
| $\mathrm{V}_{\mathrm{IH}}$ | Minimum High-Level Input Voltage | $\begin{aligned} & \mathrm{V}_{\text {out }}=0.1 \mathrm{~V} \text { or } \mathrm{V}_{\mathrm{CC}}-0.1 \mathrm{~V} \\ & \mid l_{\text {out }} \leq 20 \mu \mathrm{~A} \end{aligned}$ | $\begin{gathered} \hline 4.5 \\ \text { to } \\ 5.5 \end{gathered}$ | 2.0 | 2.0 | 2.0 | V |
| $\mathrm{V}_{\mathrm{IL}}$ | Maximum Low-Level Input Voltage | $\begin{aligned} & \mathrm{V}_{\text {out }}=0.1 \mathrm{~V} \text { or } \mathrm{V}_{\mathrm{CC}}-0.1 \mathrm{~V} \\ & \mid l_{\text {out }} \leq 20 \mu \mathrm{~A} \end{aligned}$ | $\begin{gathered} 4.5 \\ \text { to } \\ 5.5 \end{gathered}$ | 0.8 | 0.8 | 0.8 | V |
| $\mathrm{V}_{\mathrm{OH}}$ | Minimum High-Level Output Voltage, $\mathrm{Q}_{\mathrm{A}}-\mathrm{Q}_{\mathrm{H}}$ | $\begin{aligned} & \mathrm{V}_{\text {in }}=\mathrm{V}_{\mathrm{IH}} \text { or } \mathrm{V}_{\mathrm{IL}} \\ & \\|_{\text {out }} \leq 20 \mu \mathrm{~A} \end{aligned}$ | 4.5 | 4.4 | 4.4 | 4.4 | V |
|  |  | $\mathrm{V}_{\text {in }}=\mathrm{V}_{\mathrm{IH}}$ or $\mathrm{V}_{\mathrm{IL}} \quad\left\|l_{\text {out }}\right\| \leq 6.0 \mathrm{~mA}$ | 4.5 | 3.98 | 3.84 | 3.7 |  |
| $\mathrm{V}_{\text {OL }}$ | Maximum Low-Level Output Voltage, $\mathrm{Q}_{\mathrm{A}}-\mathrm{Q}_{\mathrm{H}}$ | $\begin{aligned} & \mathrm{V}_{\text {in }} \mathrm{V}_{\mathrm{IH}} \text { or } \mathrm{V}_{\mathrm{IL}} \\ & \mid l_{\text {out }} \leq 20 \end{aligned}$ | 4.5 | 0.1 | 0.1 | 0.1 | V |
|  |  | $\mathrm{V}_{\text {in }}=\mathrm{V}_{\mathrm{IH}}$ or $\mathrm{V}_{\mathrm{IL}} \quad\left\|\mathrm{l}_{\text {out }}\right\| \leq 6.0 \mathrm{~mA}$ | 4.5 | 0.26 | 0.33 | 0.4 |  |
| $\mathrm{V}_{\mathrm{OH}}$ | Minimum High-Level Output Voltage, SQ $_{\mathrm{H}}$ | $\begin{aligned} & V_{\text {in }} \mathrm{V}_{\text {IH }} \text { or } \mathrm{V}_{\mathrm{IL}} \\ & \\|_{\text {out }} \leq 20 \mu \mathrm{~A} \end{aligned}$ | 4.5 | 4.4 | 4.4 | 4.4 | V |
|  |  | $\mathrm{V}_{\text {in }}=\mathrm{V}_{\mathrm{IH}}$ or $\mathrm{V}_{\mathrm{IL}} \quad \mathrm{Il}_{\text {out }} \mathrm{I} \leq 4.0 \mathrm{~mA}$ | 4.5 | 3.98 | 3.84 | 3.7 |  |
| $\mathrm{V}_{\mathrm{OL}}$ | Maximum Low-Level Output Voltage, SQ $_{H}$ | $\begin{aligned} & \mathrm{V}_{\text {in }}=\mathrm{V}_{\mathrm{IH}} \text { or } \mathrm{V}_{\mathrm{IL}} \\ & \\|_{\text {out }} \leq 20 \mu \mathrm{~A} \end{aligned}$ | 4.5 | 0.1 | 0.1 | 0.1 | V |
|  |  | $\mathrm{V}_{\text {in }}=\mathrm{V}_{\mathrm{IH}}$ or $\mathrm{V}_{\mathrm{IL}} \quad \mathrm{Il}_{\text {out }} \leq 4.0 \mathrm{~mA}$ | 4.5 | 0.26 | 0.33 | 0.4 |  |
| $\mathrm{l}_{\text {in }}$ | Maximum Input Leakage Current | $\mathrm{V}_{\text {in }}=\mathrm{V}_{\text {cC }}$ or GND | 5.5 | $\pm 0.1$ | $\pm 1.0$ | $\pm 1.0$ | $\mu \mathrm{A}$ |
| loz | Maximum Three-State Leakage Current, $Q_{A}-Q_{H}$ | Output in High-Impedance State $\mathrm{V}_{\text {in }}=\mathrm{V}_{\mathrm{IL}}$ or $\mathrm{V}_{\mathrm{IH}}$ <br> $V_{\text {out }}=V_{\text {CC }}$ or GND | 5.5 | $\pm 0.5$ | $\pm 5.0$ | $\pm 10$ | $\mu \mathrm{A}$ |
| $\mathrm{I}_{\mathrm{CC}}$ | Maximum Quiescent Supply Current (per Package) | $\begin{aligned} & V_{\text {in }}=V_{C C} \text { or GND } \\ & I_{\text {out }}=0 \mu A \end{aligned}$ | 5.5 | 4.0 | 40 | 160 | $\mu \mathrm{A}$ |


| $\Delta_{\text {CC }}$ | Additional Quiescent Supply Current | $\begin{aligned} & \mathrm{V}_{\text {in }}=2.4 \mathrm{~V}, \text { Any One Input } \\ & \mathrm{V}_{\text {in }}=\mathrm{V}_{\mathrm{CC}} \text { or } \mathrm{GND}, \text { Other Inputs } \\ & \mathrm{I}_{\text {out }}=0 \mu \mathrm{~A} \end{aligned}$ | 5.5 | $\geq-55^{\circ} \mathrm{C}$ | 25 to $125^{\circ} \mathrm{C}$ | mA |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | 2.9 | 2.4 |  |

AC ELECTRICAL CHARACTERISTICS $\left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}\right.$, $\left.\operatorname{Input} \mathrm{t}_{\mathrm{r}}=\mathrm{t}_{\mathrm{f}}=6.0 \mathrm{~ns}\right)$

| Symbol | Parameter | $\begin{gathered} \mathrm{v}_{\mathrm{cc}} \\ \mathrm{~V} \end{gathered}$ | Guaranteed Limit |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | -55 to $25^{\circ} \mathrm{C}$ | $\leq 8^{\circ} \mathrm{C}$ | $\leq 125^{\circ} \mathrm{C}$ |  |
| $\mathrm{f}_{\text {max }}$ | Maximum Clock Frequency (50\% Duty Cycle) (Figures 1 and 7) | $\begin{gathered} 4.5 \text { to } \\ 5.5 \end{gathered}$ | 30 | 24 | 20 | MHz |
| $\begin{aligned} & \mathrm{t}_{\mathrm{PLH}}, \\ & \mathrm{t}_{\mathrm{PHL}} \end{aligned}$ | Maximum Propagation Delay, Shift Clock to $\mathrm{SQ}_{\mathrm{H}}$ (Figures 1 and 7) | $\begin{gathered} 4.5 \text { to } \\ 5.5 \end{gathered}$ | 28 | 35 | 42 | ns |
| ${ }_{\text {tPHL }}$ | Maximum Propagation Delay, Reset to $\mathrm{SQ}_{\mathrm{H}}$ (Figures 2 and 7) | $\begin{gathered} \hline 4.5 \text { to } \\ 5.5 \end{gathered}$ | 29 | 36 | 44 | ns |
| $\begin{aligned} & \hline \mathrm{t}_{\mathrm{PLLH}}, \\ & \mathrm{t}_{\mathrm{PHL}} \\ & \hline \end{aligned}$ | Maximum Propagation Delay, Latch Clock to $Q_{A}-Q_{H}$ (Figures 3 and 7) | $\begin{gathered} 4.5 \text { to } \\ 5.5 \end{gathered}$ | 28 | 35 | 42 | ns |
| $\begin{aligned} & \hline \mathrm{t}_{\mathrm{PLZ}}, \\ & \mathrm{t}_{\mathrm{PHZ}} \\ & \hline \end{aligned}$ | Maximum Propagation Delay, Output Enable to $Q_{A}-Q_{H}$ (Figures 4 and 8) | $\begin{gathered} \hline 4.5 \text { to } \\ 5.5 \end{gathered}$ | 30 | 38 | 45 | ns |
| $\begin{aligned} & \text { tpzL, } \\ & \text { tpZH } \\ & \hline \end{aligned}$ | Maximum Propagation Delay, Output Enable to $Q_{A}-Q_{H}$ (Figures 4 and 8) | $\begin{gathered} \hline 4.5 \text { to } \\ 5.5 \end{gathered}$ | 27 | 34 | 41 | ns |
| $\begin{aligned} & \mathrm{t}_{\mathrm{TLLH}}, \\ & \mathrm{t}_{\mathrm{THL}} \\ & \hline \end{aligned}$ | Maximum Output Transition Time, $\mathrm{Q}_{\mathrm{A}}-\mathrm{Q}_{\mathrm{H}}$ (Figures 3 and 7) | $\begin{gathered} 4.5 \text { to } \\ 5.5 \end{gathered}$ | 12 | 15 | 18 | ns |
| $\begin{aligned} & \mathrm{t}_{\mathrm{t} \mathrm{LH},}, \\ & \mathrm{t}_{\mathrm{TH} \mathrm{HL}} \end{aligned}$ | Maximum Output Transition Time, SQ $_{H}$ (Figures 1 and 7) | $\begin{gathered} \hline 4.5 \text { to } \\ 5.5 \end{gathered}$ | 15 | 19 | 22 | ns |
| $\mathrm{C}_{\text {in }}$ | Maximum Input Capacitance | - | 10 | 10 | 10 | pF |
| $\mathrm{C}_{\text {out }}$ | Maximum Three-State Output Capacitance (Output in High-Impedance State), $\mathrm{Q}_{\mathrm{A}}-\mathrm{Q}_{\mathrm{H}}$ | - | 15 | 15 | 15 | pF |


|  |  | Typical @ 25 ${ }^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{CC}}=5.0 \mathrm{~V}$ |  |
| :---: | :---: | :---: | :---: |
| $\mathrm{C}_{\text {PD }}$ | Power Dissipation Capacitance (Per Package)* | 300 | pF |

*Used to determine the no-load dynamic power consumption: $P_{D}=C_{P D} V_{C C}{ }^{2}+I_{C C} V_{C C}$.
TIMING REQUIREMENTS (Input $\mathrm{t}_{\mathrm{r}}=\mathrm{t}_{\mathrm{f}}=6.0 \mathrm{~ns}$ )

| Symbol | Parameter | $\mathrm{v}_{\mathrm{cc}}$ | Guaranteed Limit |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | $25^{\circ} \mathrm{C}$ to $-55^{\circ} \mathrm{C}$ | $\leq 85^{\circ} \mathrm{C}$ | $\leq 125^{\circ} \mathrm{C}$ |  |
| $\mathrm{t}_{\text {su }}$ | Minimum Setup Time, Serial Data Input A to Shift Clock (Figure 5) | $\begin{gathered} \hline 4.5 \text { to } \\ 5.5 \end{gathered}$ | 10 | 13 | 15 | ns |
| $\mathrm{t}_{\text {su }}$ | Minimum Setup Time, Shift Clock to Latch Clock (Figure 6) | $\begin{gathered} \hline 4.5 \text { to } \\ 5.5 \end{gathered}$ | 15 | 19 | 22 | ns |
| $t_{\text {h }}$ | Minimum Hold Time, Shift Clock to Serial Data Input A (Figure 5) | $\begin{gathered} 4.5 \text { to } \\ 5.5 \end{gathered}$ | 5.0 | 5.0 | 5.0 | ns |
| $\mathrm{t}_{\text {rec }}$ | Minimum Recovery Time, Reset Inactive to Shift Clock (Figure 2) | $\begin{gathered} \hline 4.5 \text { to } \\ 5.5 \end{gathered}$ | 10 | 13 | 15 | ns |
| $\mathrm{t}_{\text {w }}$ | Minimum Pulse Width, Reset (Figure 2) | $\begin{gathered} 4.5 \text { to } \\ 5.5 \end{gathered}$ | 12 | 15 | 18 | ns |
| $\mathrm{t}_{\text {w }}$ | Minimum Pulse Width, Shift Clock (Figure 1) | $\begin{gathered} 4.5 \text { to } \\ 5.5 \end{gathered}$ | 10 | 13 | 15 | ns |
| $\mathrm{t}_{\text {w }}$ | Minimum Pulse Width, Latch Clock (Figure 6) | $\begin{gathered} \hline 4.5 \text { to } \\ 5.5 \end{gathered}$ | 10 | 13 | 15 | ns |
| $\mathrm{tr}_{\mathrm{r}} \mathrm{t}_{\mathrm{f}}$ | Maximum Input Rise and Fall Times (Figure 1) | $\begin{gathered} \hline 4.5 \text { to } \\ 5.5 \end{gathered}$ | 500 | 500 | 500 | ns |

## FUNCTION TABLE

| Operation | Inputs |  |  |  |  | Resulting Function |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | Reset | Serial Input A | Shift <br> Clock | Latch Clock | Output <br> Enable | Shift Register Contents | Latch Contents | Serial Output $S_{H}$ | Parallel Outputs $Q_{A}-Q_{H}$ |
| Reset shift register | L | X | X | L, H, $\downarrow$ | L | L | U | L | U |
| Shift data into shift register | H | D | $\uparrow$ | L, H, $\downarrow$ | L | $\begin{gathered} \mathrm{D} \rightarrow \mathrm{SR}_{\mathrm{A}} ; \\ \mathrm{SR}_{\mathrm{N}} \rightarrow \mathrm{SR}_{\mathrm{N}+1} \end{gathered}$ | U | $\mathrm{SR}_{\mathrm{G}} \rightarrow \mathrm{SR}_{\mathrm{H}}$ | U |
| Shift register remains unchanged | H | X | L, H, $\downarrow$ | L, H, $\downarrow$ | L | U | U | U | U |
| Transfer shift register contents to latch register | H | X | L, H, $\downarrow$ | $\uparrow$ | L | U | $\mathrm{SR}_{\mathrm{N}} \rightarrow \mathrm{LR}_{\mathrm{N}}$ | U | $\mathrm{SR}_{\mathrm{N}}$ |
| Latch register remains unchanged | X | X | X | L, H, $\downarrow$ | L | * | U | * | U |
| Enable parallel outputs | X | X | X | X | L | * | ** | * | Enabled |
| Force outputs into high impedance state | X | X | X | X | H | * | ** | * | Z |
| SR = shift register conte <br> LR = latch register conte | $D=$ data (L, H) logic level <br> $\mathrm{U}=$ remains unchanged |  |  |  | $\begin{array}{ll} \uparrow=\text { Low-to-High } & * \\ \downarrow=\text { High-to-Low } & * * \end{array}$ |  | * = depends on Reset and Shift Clock inputs <br> ** $=$ depends on Latch Clock input |  |  |

## PIN DESCRIPTIONS

## INPUTS

## A (Pin 14)

Serial Data Input. The data on this pin is shifted into the 8-bit serial shift register.

## CONTROL INPUTS

## Shift Clock (Pin 11)

Shift Register Clock Input. A low- to-high transition on this input causes the data at the Serial Input pin to be shifted into the 8 -bit shift register.

## Reset (Pin 10)

Active-low, Asynchronous, Shift Register Reset Input. A low on this pin resets the shift register portion of this device only. The 8-bit latch is not affected.

## Latch Clock (Pin 12)

Storage Latch Clock Input. A low-to-high transition on this input latches the shift register data.

## Output Enable (Pin 13)

Active-low Output Enable. A low on this input allows the data from the latches to be presented at the outputs. A high on this input forces the outputs $\left(\mathrm{Q}_{\mathrm{A}}-\mathrm{Q}_{\mathrm{H}}\right)$ into the high-impedance state. The serial output is not affected by this control unit.

## OUTPUTS

$Q_{A}-Q_{H}($ Pins 15, 1, 2, 3, 4, 5, 6, 7)
Noninverted, 3-state, latch outputs.

## $\mathbf{S Q}_{\mathrm{H}}(\operatorname{Pin} 9)$

Noninverted, Serial Data Output. This is the output of the eighth stage of the 8 -bit shift register. This output does not have three-state capability.

## MC74HCT595A

## SWITCHING WAVEFORMS

$$
\left(\mathrm{V}_{\mathrm{I}}=0 \text { to } 3 \mathrm{~V}, \mathrm{~V}_{\mathrm{M}}=1.3 \mathrm{~V}\right)
$$



Figure 1.


Figure 3.


Figure 5.


Figure 2.


Figure 4.


Figure 6.

## TEST CIRCUITS



EXPANDED LOGIC DIAGRAM


TIMING DIAGRAM


SCALE 1:1


| STYLE 1: |  |
| ---: | :--- |
| PIN 1. | COLLECTOR |
| 2. | BASE |
| 3. | EMITTER |
| 4. | NO CONNECTION |
| 5. | EMITTER |
| 6. | BASE |
| 7. | COLLECTOR |
| 8. | COLLECTOR |
| 9. | BASE |
| 10. | EMITTER |
| 11. | NO CONNECTION |
| 12. | EMITTER |
| 13. | BASE |
| 14. | COLLECTOR |
| 15. | EMITTER |
| 16. | COLLECTOR |


| STYLE 2: |  |
| ---: | :--- |
| PIN 1. | CATHODE |
| 2. | ANODE |
| 3. | NO CONNECTION |
| 4. | CATHODE |
| 5. | CATHODE |
| 6. | NO CONNECTION |
| 7. | ANODE |
| 8. | CATHODE |
| 9. | CATHODE |
| 10. | ANODE |
| 11. | NO CONNECTION |
| 12. | CATHODE |
| 13. | CATHODE |
| 14. | NO CONNECTION |
| 15. | ANODE |
| 16. | CATHODE |


| STYLE 3: |  | STYLE 4: |  |
| ---: | :--- | ---: | :--- |
| PIN 1. | COLLECTOR, DYE \#1 | PIN 1. | COLLECTOR, DYE \#1 |
| 2. | BASE, \#1 | 2. | COLLECTOR, \#1 |
| 3. | EMITTER, \#1 | 3. | COLLECTOR, \#2 |
| 4. | COLLECTOR, \#1 | 4. | COLLECTOR, \#2 |
| 5. | COLLECTOR, \#2 | 5. | COLLECTOR, \#3 |
| 6. | BASE, \#2 | 6. | COLLECTOR, \#3 |
| 7. | EMITTER, \#2 | 7. | COLLECTOR, \#4 |
| 8. | COLLECTOR, \#2 | 8. | COLLECTOR, \#4 |
| 9. | COLLECTOR, \#3 | 9. | BASE, \#4 |
| 10. | BASE, \#3 | 10. | EMITTER, \#4 |
| 11. | EMITTER, \#3 | 11. | BASE, \#3 |
| 12. | COLLECTOR, \#3 | 12. | EMITTER, \#3 |
| 13. | COLLECTOR, \#4 | 13. | BASE, \#2 |
| 14. | BASE, \#4 | 14. | EMITTER, \#2 |
| 15. | EMITTER, \#4 | 15. | BASE, \#1 |
| 16. | COLLECTOR, \#4 | 16. | EMITTER, \#1 |

SOLDERING FOOTPRINT
15.
16. CATHODE STYLE 5:
PIN 1. DRAIN, DYE \#1
STYLE 6:
PIN 1. CATHODE
2. DRAIN, \#1
3. DRAIN, \#2
4. DRAIN, +2
5. DRAIN, \#3
6. DRAIN, \#3
7. DRAIN, \#4

CATHODE

- 8. CATHODE

10. SOURCE, \#4
$\begin{array}{lll}\text { 10. } & \text { SOURCE, \#4 } & \text { 10. ANODE } \\ \text { 11. GATE, \#3 } & \text { 11. ANODE } & \text { 10. COMMON DRAIN (OUTPUT) }\end{array}$
. ANODE
STYLE 7:
PIN 1. SOURCE N-CH
11. COMMON DRAIN (OUTPUT)
12. COMMON DRAIN (OUTPUT)
13. GATE P-CH
14. COMMON DRAIN (OUTPUT)
15. COMMON DRAIN (OUTPUT)
16. COMMON DRAIN (OUTPUT)
17. COMMON DRAIN (OUTPUT)
18. SOURCE, \#3 12. ANODE 12. COMMON DRAIN (OUTPUT)
$\begin{array}{lll}\text { 13. } \text { GATE, \#2 } & \text { 13. ANODE } & \text { 13. GATE N-CH } \\ \text { 14. SOURCE, \#2 } & \text { 14. ANODE } & \text { 14. COMMON DRAIN (OUTPUT) }\end{array}$
$\begin{array}{lll}\text { 14. SOURCE, \#2 } & \text { 14. ANODE } & \text { 14. COMMON DRAIN (OUTPUT) } \\ \text { 15. GATE, } \# 1 & \text { 15. ANODE } & \text { 15. COMMON DRAIN (OUTPUT) }\end{array}$
19. SOURCE, \#1
20. ANODE
21. SOURCE N-CH

NOTES

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION PROTRUSION. ALLOWABLE DAMBAR PROTRUSION
SHALL BE $0.127(0.005)$ TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

| DIM | MILLIMETERS |  | INCHES |  |
| :---: | :---: | ---: | ---: | ---: |
|  | MIN | MAX | MIN | MAX |
| A | 9.80 | 10.00 | 0.386 | 0.393 |
| B | 3.80 | 4.00 | 0.150 | 0.157 |
| C | 1.35 | 1.75 | 0.054 | 0.068 |
| D | 0.35 | 0.49 | 0.014 | 0.019 |
| F | 0.40 | 1.25 | 0.016 |  |
| G | 1.27 |  | 0.049 |  |
| J | 0.19 | 0.25 | 0.050 |  |
| K | 0.10 | 0.25 | 0.009 |  |
| M | 0.0 | 0.004 | 0.009 |  |
| P | 5.80 | 6.20 | 0.229 | $7^{\circ}$ |
| R | 0.25 | 0.50 | 0.244 |  |


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| ---: | :--- | :--- | :--- |
| DESCRIPTION: | SOIC-16 | PAGE 1 OF 1 |

[^1]

TSSOP-16
CASE 948F-01
ISSUE B
DATE 19 OCT 2006
SCALE 2:1


## NOTES

DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 ( 0.006 ) PER SIDE
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 ( 0.010 ) PER SIDE
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-

| DIM | MILLIMETERS |  | INCHES |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | MIN | MAX | MIN | MAX |  |  |
| A | 4.90 | 5.10 | 0.193 | 0.200 |  |  |
| B | 4.30 | 4.50 | 0.169 | 0.177 |  |  |
| C | --- | 1.20 | --- | 0.047 |  |  |
| D | 0.05 | 0.15 | 0.002 | 0.006 |  |  |
| F | 0.50 | 0.75 | 0.020 | 0.030 |  |  |
| G | 0.65 |  | BSC | 0.026 |  | BSC |
| H | 0.18 | 0.28 | 0.007 | 0.011 |  |  |
| J | 0.09 | 0.20 | 0.004 | 0.008 |  |  |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |  |  |
| K | 0.19 | 0.30 | 0.007 | 0.012 |  |  |
| K1 | 0.19 | 0.25 | 0.007 |  |  |  |
| L | 6.40 |  | BSC | 0.010 |  |  |
| M | 0 |  | 0.252 | $8^{\circ}$ |  |  |

SOLDERING FOOTPRINT


GENERIC MARKING DIAGRAM*


| XXXX | $=$ Specific Device Code |
| :--- | :--- |
| A | $=$ Assembly Location |
| L | $=$ Wafer Lot |
| Y | $=$ Year |
| W | $=$ Work Week |
| Gor v | $=$ Pb-Free Package |

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

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| ---: | :--- | :--- | :--- |
| DESCRIPTION: | TSSOP-16 | PAGE 1 OF 1 |

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74HC194D,653 74HCT164DB. 118 74HCT4094D. 112 74LV164DB. 112 74LVC594AD. 112 HEF4094BT.653 74VHC164FT(BE)
74HCT594DB. 112 74HCT597DB. 112 74LV164D. 112 74LV165D. 112 74LV4094D. 112 74LV4094PW. 112 CD74HC165M 74AHC594T16-
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[^0]:    *For additional information on our $\mathrm{Pb}-$ Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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